

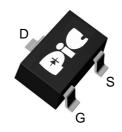
## General Description

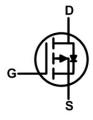
This PAP4111N P-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

### > Feature

- ●Super Low Gate Charge
- ●Green Device Available
- ●Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- ●SOT-23 Package design

### > **SOT-23**





## > Application

- ■Load Switch
- Portable instrument
- ●MB / NB / 3C device

## > Absolute Maximum Ratings

Parameter	Obl	Ra	nting		
	Symbol	10s	Steady State	Units	
Drain-Source Voltage	V <sub>DS</sub>	-40		V	
Gate-Source Voltage	V <sub>G</sub> s	±20		V	
Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =25℃	-3.7	-3.2	А	
Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =70°C	-3.0	-2.6	А	
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	-16.1		А	
Total Power Dissipation <sup>3</sup>	P <sub>D</sub> @T <sub>A</sub> =25℃	1.32	1	W	
Total Power Dissipation <sup>3</sup>	P <sub>D</sub> @T <sub>A</sub> =70°C	0.84	0.64	W	
Storage Temperature Range	T <sub>STG</sub>	-55 to 150		$^{\circ}$ C	
Operating Junction Temperature Range	TJ	-55 to 150		$^{\circ}$ C	
Thermal Resistance Junction-Ambient <sup>1</sup>	RθJA	125		°C/W	
Thermal Resistance Junction-Ambient ¹ (t ≤10s)	R <sub>θJA</sub>	95		°C/W	
Thermal Resistance Junction-Case <sup>1</sup>	R <sub>0JC</sub>	80		°C/W	



## Electrical Characteristics (T<sub>J</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-40			V	
BV <sub>DSS</sub> Temperature Coefficient	Δ BV <sub>DSS</sub> /Δ T <sub>J</sub>	Reference to 25℃ , I <sub>D</sub> =-1mA		-0.018		V/℃	
Static Drain-Source On-Resistance <sup>2</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-3A			70		
	KDS(ON)	V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-2A			100	mΩ	
Gate Threshold Voltage	V <sub>GS(th)</sub>	Vgs=Vps . In =-250uA	-1.0		-2.5	V	
V <sub>GS(th)</sub> Temperature Coefficient	Δ V <sub>GS(th)</sub>	VGS=VDS, ID =-250UA		2.5		mV/℃	
Drain-Source Leakage Current  IDSS  VDS=-24V , VGS=0V , TJ=25°C  VDS=-24V , VGS=0V , TJ=55°C	1	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃		-1	_		
			-5	uA			
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA	
Forward Transconductance	gfs	V <sub>DS</sub> =-5V , I <sub>D</sub> =-3A		5.8		S	
Total Gate Charge (-4.5V)	Qg			6.4		nC	
Gate-Source Charge	Qgs	V <sub>DS</sub> =-32V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-3A		2.1			
Gate-Drain Charge	$Q_{gd}$			2.5			
Turn-On Delay Time	T <sub>d(on)</sub>			4.2			
Rise Time	Tr	V <sub>DD</sub> =-20V , V <sub>GS</sub> =-4.5V ,		23		ns	
Turn-Off Delay Time	T <sub>d(off)</sub>	R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-3A		26.8			
Fall Time	Tf			20.6			
Input Capacitance	C <sub>iss</sub>			620			
Output Capacitance	Coss	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		65		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			53			

# Diode Characteristics

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous Source Current <sup>1,4</sup>	Is	V V OV Force Comment			-3.2	Α
Pulsed Source Current <sup>2,4</sup>	Ism	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-16.1	Α
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1	V

#### Note:

<sup>1.</sup>Pulse width limited by maximum junction temperature.

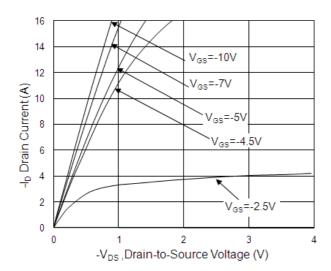
<sup>2.</sup>The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%

<sup>3.</sup>Ensure that the channel temperature does not exceed 150  $^{\circ}\text{C}.$ 

<sup>4.</sup>The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



# > Typical Characteristics



**Fig.1 Typical Output Characteristics** 

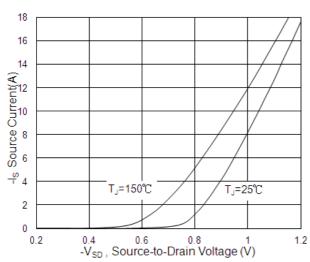


Fig.3 Forward Characteristics Of Reverse

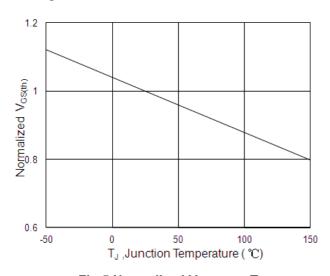


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>blce</sub>.

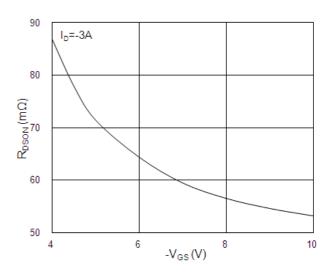


Fig.2 On-Resistance vs. G-S Voltage

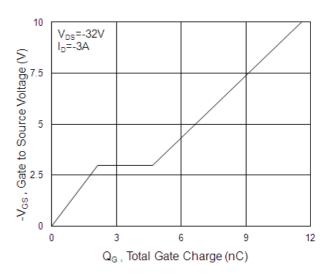


Fig.4 Gate-Charge Characteristics

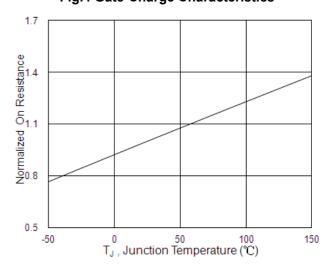
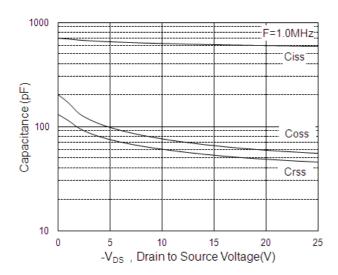


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





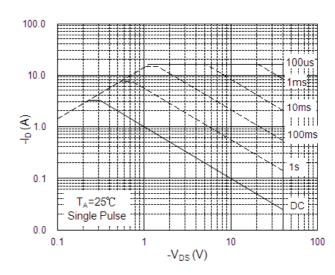


Fig.7 Capacitance

Fig.8 Safe Operating Area

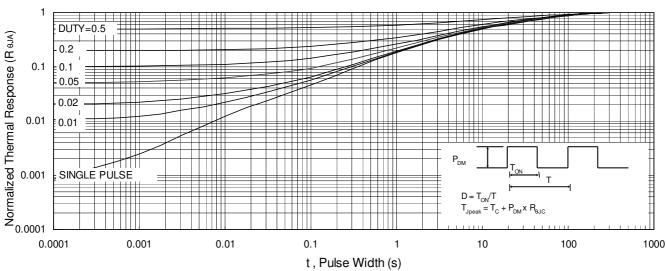
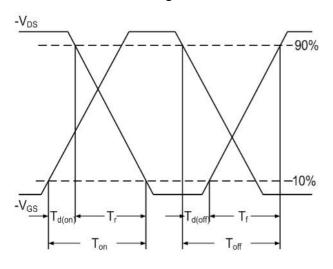


Fig.9 Normalized Maximum Transient Thermal Impedance



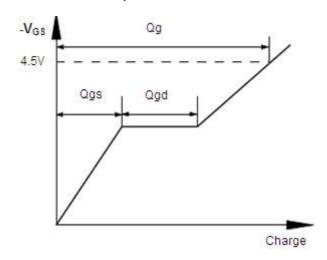
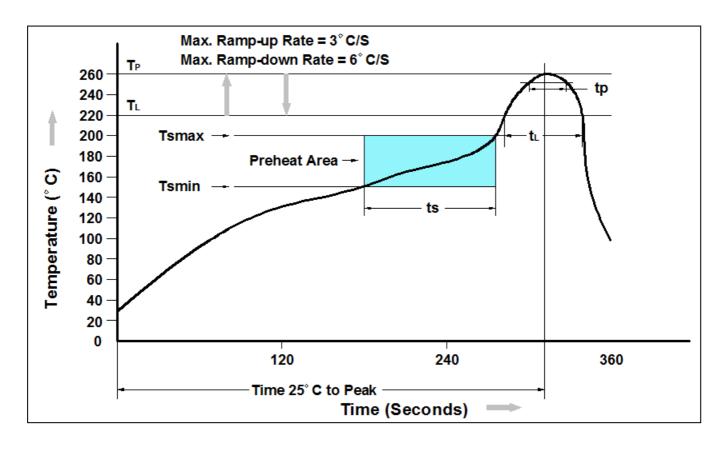


Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform



# Recommand IR Reflow Soldering Thermal Profile



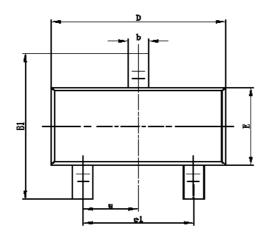
Profile Feature	Pb-Free Assembly Profile		
Temperature Min. (Tsmin)	150°C		
Temperature Max. (Tsmax)	200°C		
Time (ts) from (Tsmin to Tsmax)	60-120 seconds		
Average Ramp-up Rate (tL to tP)	3°C/second max.		
Liquidous Temperature (TL)	217°C		
Time (tL) Maintained Above (TL)	60 – 150 seconds		
Peak Temperature	260°C +0°C /-5°C		
Time (tP) within 5°C of actual Peak Temperature	30 seconds		
Ramp-down Rate (TP to TL)	6°C/second max		
Time 25°C to Peak Temperature	8 minutes max.		

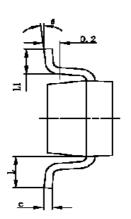
# Ordering Information

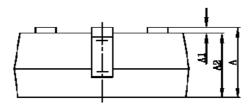
Part Number	Description	Quantity
PAP4111N	SOT-23 Reel	3000 pcs



# Package Information (SOT-23)







Camah al	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.400	0.012	0.016	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950	OTYP	0.03	7TYP	
e1	1.800	2.000	0.071	0.079	
L	0.700	REF 0.028REF		BREF	
L1	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	





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